

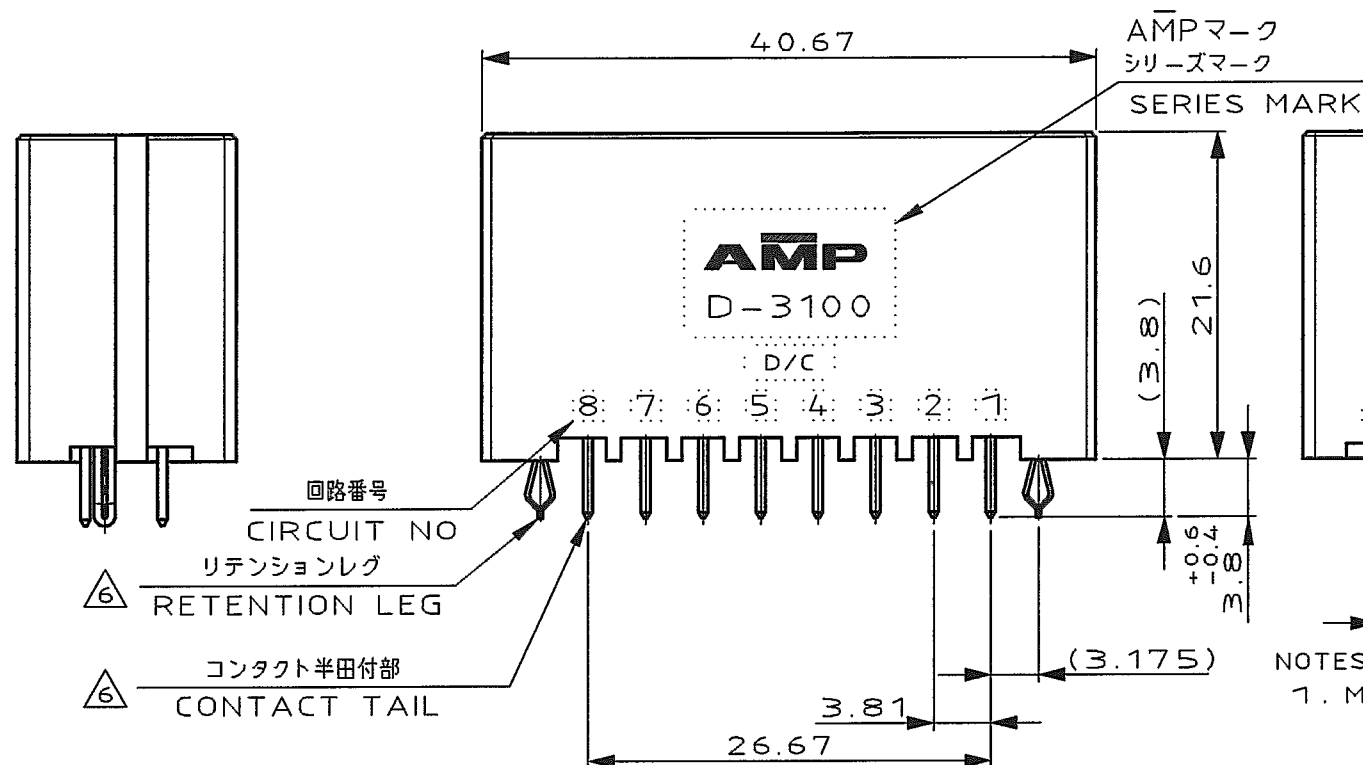
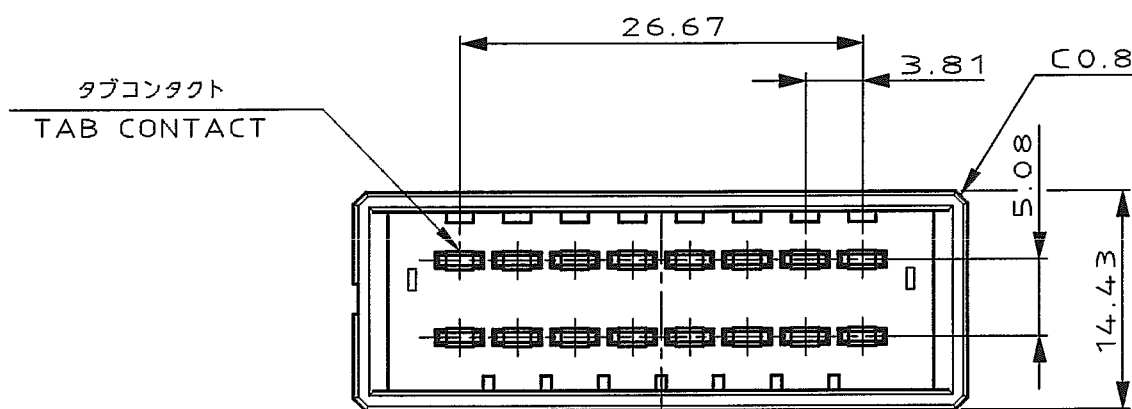
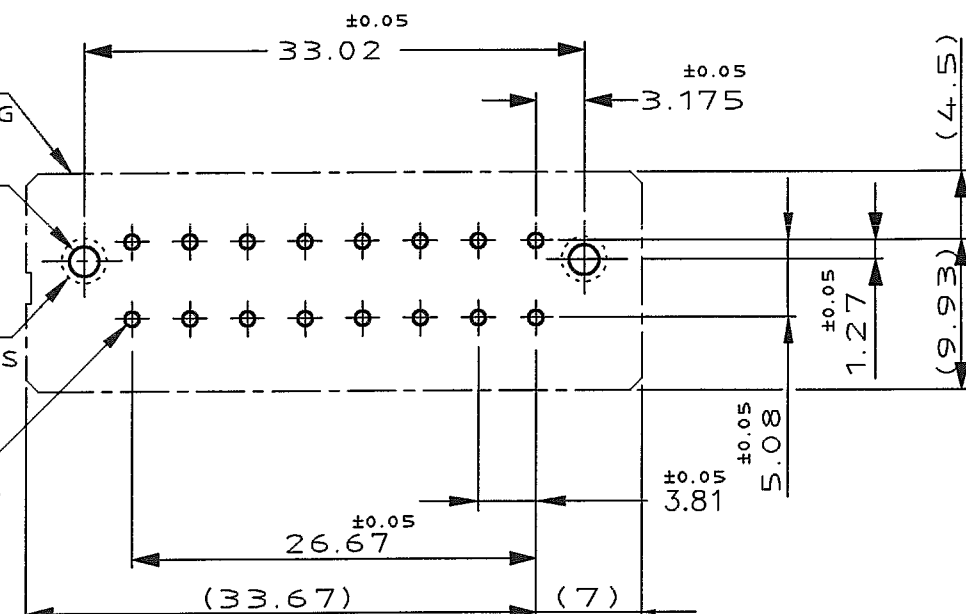
NUMBER 178327



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

コネクタ外形
OUTLINE OF HEADER HOUSINGスルーホール 2-φ2
DIA2±0.1 2PLACESラウンド 2-φ3MIN
ROUND DIA3MIN 2PLACES16-φ1.1
DIA1.1±0.1 16PLACES

推奨基板取付け寸法

PC 基板厚:1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN

PC BOARD THICKNESS:1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

- MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC,POLYESTER(94V-0),COLOR:BLACK
CONTACT:CUPPER ALLOY
RETENTION LEG:CUPPER ALLOY
- FINISH(CONTACT AREA):0.38μmMIN GOLD PLATING OVER Ni PLATING
- FINISH(CONTACT AREA):0.76μmMIN GOLD PLATING OVER Ni PLATING
- FINISH(CONTACT AREA):2.0 μmMIN TIN PLATED OVER NICKEL
- FINISH(RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH(RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料:ハウジング:ガラス入り熱可塑性ポリエスデル樹脂 (94V-0),色:黒
コンタクト:銅合金
リテンションレグ:銅合金
- めっき:コンタクト:全面Ni下地
接触部:0.38μm MIN金めっき
- めっき:コンタクト:全面Ni下地
接触部:0.76μm MIN金めっき
- めっき:コンタクト:全面Ni下地
接触部:2.0 μm MINスズめっき
- めっき:リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき
- めっき:リテンションレグとコンタクト半田付部
ニッケル下地の上にスズめっき

△6	△4	178327-5
△6	△3	178327-3
△6	△2	178327-2
(FINISH)		製品番号 (PART NO.)

E	REVISED	FJDO-0039-03	T S S M	8/2 '93
D	REVISED	FJDO-0114-03	T S S M	25 APR '93
C	REVISED	FJ00-2744-95	K I Y I	16 JUN '95
B	REVISED	FJ00-0838-94	N M S M	7/4 '94
A	REDRAWN WITH CHANGE	FJ00-0480-94	N M S M	4/20 '94
LTR	REVISION RECORD		DR	CHK DATE

Copyright © 1994
AMP(Japan) LTD.
ALL RIGHTS RESERVED.tyco
ElectronicsTyco Electronics AMP K.K.
Kawasaki, Japan

WIRE RANGE		INSULATION DIA		NAME	
mm²(AWG -)		mmφ		16 POS DOUBLE ROW	
MATERIAL		FINISH		VERTICAL HDR ASS'Y FOR DYNAMIC D-3100	
SEE NOTE 注記参照		SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	
DR. 19 APR 94 N. Matsubara		DE. 19 APR 94 N. Matsubara		SIZE LOC NUMBER	
CHK. 20 APR 94 S. MANABE		APP. 20 APR 94 S. MANABE		10mm ±0.3 10mm 30mm ±0.4 30mm 100mm ±0.45 角 度 ±3°	
				SCALE 2-1	
				REV. E	
				SHEET 1 OF 1	

(CUSTOMER DRAWING) 顧客用図面